External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00222	0.74	0.11544
	Doped silicon	Silicon (Si)	7440-21-3	0.29729	99.26	15.48456
			Subtotal	0.29951	100	15.6
Solder Wire	Pure metal	Tin (Sn)	7440-31-5	0.0192	5.0	1
	Pure metal	Silver (Ag)	7440-22-4	0.00576	1.5	0.3
	Pure metal	Lead (Pb)	7439-92-1	0.35902	93.5	18.7
			Subtotal	0.38398	100	20
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.13439	100.0	7
			Subtotal	0.13439	100	7
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01906	0.03	0.993
	Copper alloy	Iron (Fe)	7439-89-6	0.06355	0.1	3.31
	Copper alloy	Copper (Cu)	7440-50-8	63.46613	99.87	3305.697
			Subtotal	63.54874	100	3310
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.67197	100.0	35
			Subtotal	0.67197	100	35
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.57326	4.5	81.945
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.49614	10.0	182.1
	Filler	Silica fused	60676-86-0	26.22106	75.0	1365.75
	Metal hydroxide	Metal hydroxide		3.49614	10.0	182.1
	Carbon Black	Carbon black	1333-86-4	0.17481	0.5	9.105
			Subtotal	34.96141	100	1821
			Total	100	100	5208.6

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